



Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model

[List multiple models if applicable.]

Name / Model #1 HP Elite 7000 MT Series PCs

Name / Model #2

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		4
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Phillips screwdriver	
Description #2 Dikes	
Description #3 Torx screwdriver	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

- To remove the access panel (see Figure 1):
 - Remove the screw (1) that secures the access panel to the computer chassis.
 - Slide the access panel back (2) about 1.3 cm (1/2 inch), then lift it off the unit.
- To remove the front bezel, press outward on the three latches on the right side of the bezel (1), then rotate the right side of the bezel off the chassis (2) followed by the left side (see Figure 2).
- To remove the battery:

Locate the battery and battery holder on the system board. Depending on the type of battery holder on the system board, complete the following instructions to remove the battery.

TYPE 1 BATTERY HOLDER (see Figure 3):
Lift the battery out of the holder.

TYPE 2 BATTERY HOLDER (see Figure 4):
To release the battery from its holder, squeeze the metal clamp that extends above one edge of the battery. When the battery pops up, lift it out.

TYPE 3 BATTERY HOLDER (see Figure 5):
Pull back on the clip that holds the battery in place, and then remove the battery.
- To remove the system board:
 - Disconnect all data and power cables from the system board.
 - Remove the heat sink by disconnecting the cable from the system board (1) and loosening the four captive screws that secure the heat sink to the system (see Figure 6).
 - Remove the eight screws that secure the system board to the chassis (see Figure 7).
 - Lift up the front of the system board, and then pull the system board forward, up, and out of the chassis.
- To remove the power supply:
 - Disconnect all power cables from all devices.
 - Remove the four silver T15 screws that connect the power supply to the chassis (see Figure 8).
 - Press the tab on the base pan in front of the power supply that holds it in place (see Figure 9).
 - Slide the power supply toward the front of the computer, rotate toward the fan so the power supply clears the lip on the top of the chassis, and then lift the power supply out of the chassis.
- Power supply internal components:
 - Using dikes, cut the plastic clamp that secures the wires to the power supply cover.
 - Using a phillips screwdriver, remove the six screws that secure the cover to the power supply chassis (see Figure 10).
 - Slide the cover off the power supply.
 - Using dikes, cut all cables connected to the PCA in the power supply.
 - Remove the four screws (one screw in each corner) that secure the power supply PCA to the chassis.
 - Remove the power supply PCA from the power supply chassis.
 - Cut the small PCA and four capacitors from the PCA as shown in Figure 11.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

FIGURE 1: Removing the access panel



FIGURE 2: Removing the front bezel



FIGURE 3: Type 1 battery holder

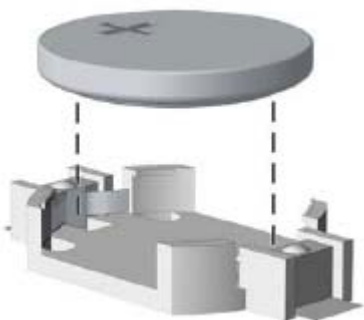


FIGURE 4: Type 2 battery holder

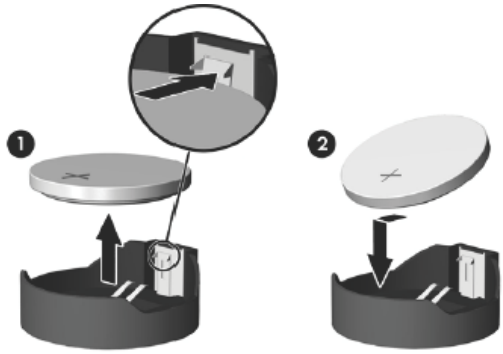


FIGURE 5: Type 3 battery holder

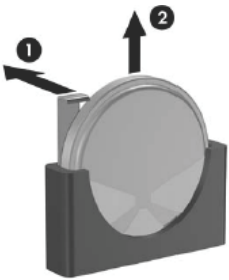


FIGURE 6: Removing the heat sink

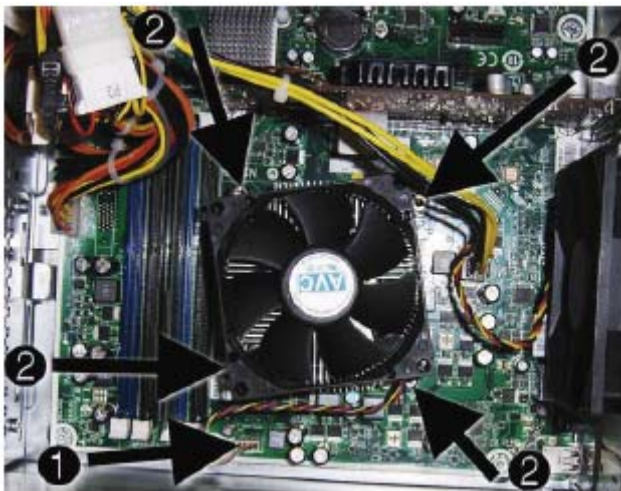


FIGURE 7: System board screw locations



FIGURE 8: Removing the power supply, screw locations

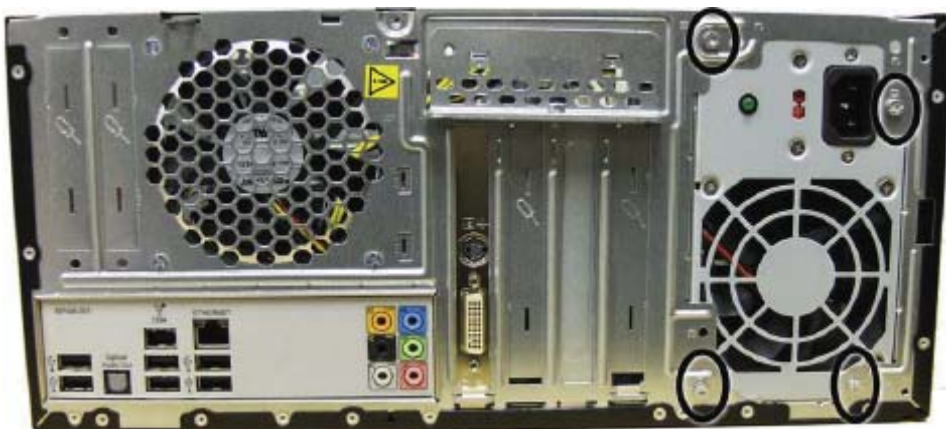


FIGURE 9: Power supply lever location



FIGURE 10: POWER SUPPLY: Screw locations



FIGURE 11: POWER SUPPLY: Capacitors to cut

